

Title (en)

METHOD AND DEVICE FOR SEPARATING SLICED WAFERS

Title (de)

VORRICHTUNG UND VERFAHREN ZUR TRENNUNG VON WAFERSCHEIBEN

Title (fr)

PROCÉDÉ ET DISPOSITIF POUR SÉPARER DES PLAQUETTES TRANCHÉES

Publication

**EP 2358618 A1 20110824 (EN)**

Application

**EP 09827257 A 20091105**

Priority

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- GB 0821357 A 20081121
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Abstract (en)

[origin: WO2010058388A1] An apparatus for separating a front wafer from a stack of wafers is disclosed. The apparatus includes a chuck for gripping the front wafer, coupled to a mechanical arm and rotatable about at least one axis with respect to the arm, so as to allow the chuck to align substantially parallel to the front wafer. A fixing mechanism is provided for fixing the chuck in a desired orientation. The apparatus also includes a drive for moving the arm in at least in two directions, one direction to bring the chuck to the front wafer and in another direction substantially parallel to the fixed orientation of the chuck to separate the wafer from the stack of wafers. A stopper mechanism is provided for preventing other wafers from separating from the stack while the front wafer is being separated.

IPC 8 full level

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CPC (source: EP KR)

**B28D 5/0082** (2013.01 - KR); **B65G 59/062** (2013.01 - EP KR); **B65G 59/08** (2013.01 - EP KR); **H01L 21/67092** (2013.01 - KR); **H01L 21/6831** (2013.01 - KR); **H01L 21/6835** (2013.01 - KR)

Citation (search report)

See references of WO 2010058388A1

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